

You are invited! Visit TRI booth **E17-20** at NEPCON JAPAN 2016 on **January 13-15, 2016** at the Tokyo Big Sight for an on-site demonstration of the latest 3D inspection and testing systems designed for **0250125mm** chips in data-driven, automated **industry 4.0** production lines.

Test Research, Inc. (TRI) returns to NEPCON Japan in 2016 with new, powerful 3D SPI, 3D AOI and CT AXI solutions lineup for inspecting and testing PCB assemblies.

Reserve your own private tour for the best experience!

AOI

NEW!

TR7700QI 3D AOI



- Stop&Go Inline 3D AOI
- Quad DLP 3D Technology
- Micro Component Ready (0250125mm)
- 20 mm Adaptive 3D Range

NEW!

TR7500 SIII AOI



- High Speed Inline AOI
- Multi Angle 6.5 Mpix Cameras
- Dynamic Imaging 70 cm²/sec @ 10 μm
- Foreign Matter Inspection

TR7700 SII Plus AOI



- World's First Hybrid 2D AOI
- Stop-and-Go/ Dynamic Imaging
- High Component Clearance
- Foreign Matter Inspection

SPI

NEW!

TR7007QI 3D SPI



- High Speed Stop-and-Go SPI
- Quad DLP Fringe Technology
- 6/8/10/15 μm Resolution
- Micro Component Ready (0250125mm)

ICT

NEW!

TR5001 SII INLINE ICT



- Parallel Multi-Core Inline ICT
- Flexible Core Merging
- 1:1 Per Pin Driver & Receiver
- QDI Fixture Connection

TR5001T SII TINY ICT



- Most Powerful Tiny ICT
- Multi-ICT Parallel Testing
- Boundary Scan Test
- Serial Device Programming

AXI

NEW!

TR7600 SII CT 3D AXI

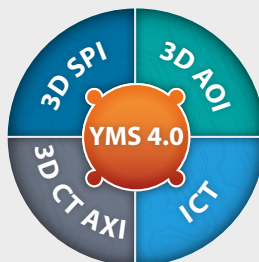


- High Speed Inline 3D AXI
- Planar 3D CT Imaging
- BGA/PoP, Press-Fit, PTH, QFN
- 3D Slicing Inspection

YMS

NEW!

YMS 4.0 Yield Management System



- Intelligent Line Management
- SPI, AOI, AXI, ICT Integration
- Remote Control and Monitoring
- Remote SPC Analysis and Control
- Industry 4.0 Quality Improvement
- OEE Monitoring
- KANBAN Realtime Monitoring
- Productivity Analysis